

## PEREGRINE MATERIAL DECLARATION FORM

<b>Product:</b>	PE42440
<b>Ordering Codes:</b>	PE42440MLBB-Z
<b>Description:</b>	SP4T UltraCMOS RF Switch 50 - 3000 MHz
<b>Package:</b>	16L 3x3 QFN
<b>Environmental Compliance</b>	EU RoHS2 Directive 2011/65/EC, REACH - EU ECHA SVHC, Arsenic Free, JIG 101 - EIA/EICTA/JEITA, Halogen Free - IEC61249-2-21, PFOS Free - 2006/122/EC, Antimony Trioxide Free
<b>Lead Finish</b>	NiPdAu
<b>Availability</b>	Now

Component	Material	CAS Number	Weight (mg)	%	PPM
SOI Wafer	Aluminum oxide	1344-28-1	0.839326	3.69%	36,886.60
SOI Wafer	Aluminum	7429-90-5	0.002553	0.01%	112.20
SOI Wafer	Silicon	7440-21-3	0.000170	0.00%	7.48
SOI Wafer	Arsenic	7440-38-2	0.000001	0.00%	0.04
SOI Wafer	Boron	7440-42-8	0.000001	0.00%	0.04
SOI Wafer	Phosphorus	7723-14-0	0.000003	0.00%	0.15
SOI Wafer	Titanium	7440-32-6	0.000426	0.00%	18.70
SOI Wafer	Tungsten	7440-33-7	0.008510	0.04%	374.00
SOI Wafer	Cobalt	7440-48-4	0.000017	0.00%	0.75
SOI Wafer	Copper	7440-50-8	0.000007	0.00%	0.30
Leadframe	Copper	7440-50-8	9.054500	39.79%	397,926.30
Leadframe	Chromium	7440-47-3	0.022800	0.10%	1,002.01
Leadframe	Tin	7440-31-5	0.022800	0.10%	1,002.01
Leadframe	Zinc	7440-66-6	0.020100	0.09%	883.35
Die Attach	Silver	7440-22-4	0.135200	0.59%	5,941.76
Die Attach	2-Butoxyethyl Acetate	112-07-2	0.015200	0.07%	668.01
Die Attach	2-Propenoic acid, 3-(trimethoxysilyl)propy	4369-14-6	0.001500	0.01%	65.92
Wire	Gold	7440-57-5	0.160600	0.71%	7,058.03
Plating	Nickel	7440-02-0	0.066600	0.29%	2,926.93
Plating	Palladium	5/3/7440	0.005400	0.02%	237.32
Plating	Gold	7440-57-5	0.000200	0.00%	8.79
Mold Compound	Silica Fused	60676-86-0	11.369300	49.97%	499,656.91
Mold Compound	Epoxy Resin	Trade secret	0.495900	2.18%	21,793.77
Mold Compound	Phenol Resin	Trade secret	0.495900	2.18%	21,793.77
Mold Compound	Carbon Black	1333-86-4	0.037200	0.16%	1,634.86
<b>Total Weight (mg)</b>			<b>22.754213</b>	100.00%	1,000,000